Extreme Ultraviolet Radiation: A Versatile Tool For Nanometrology

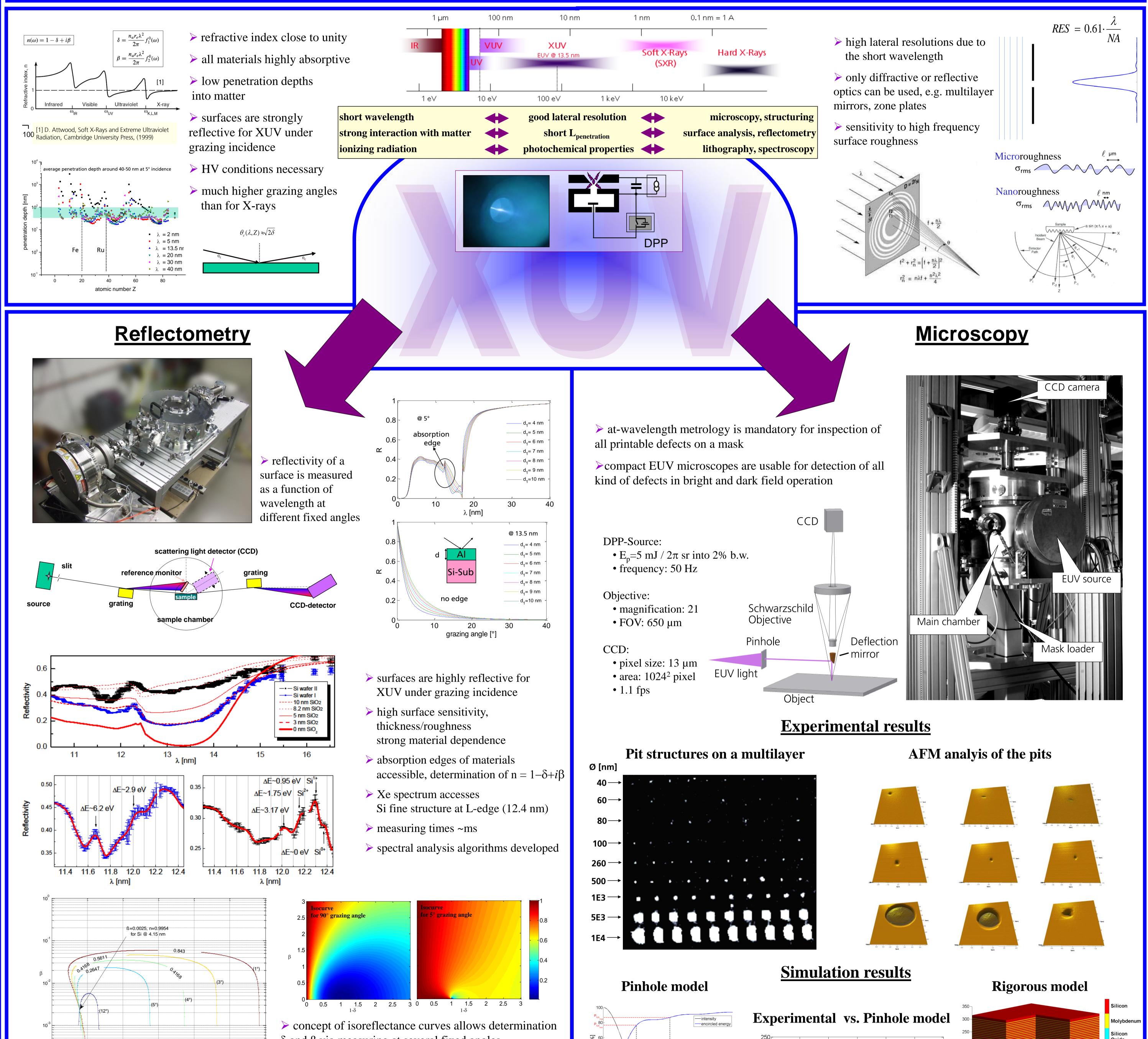


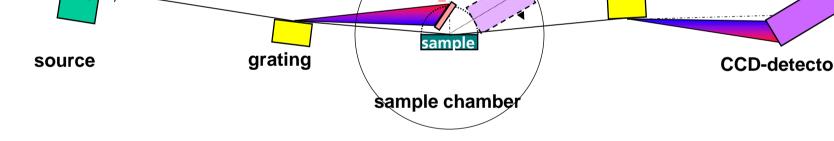
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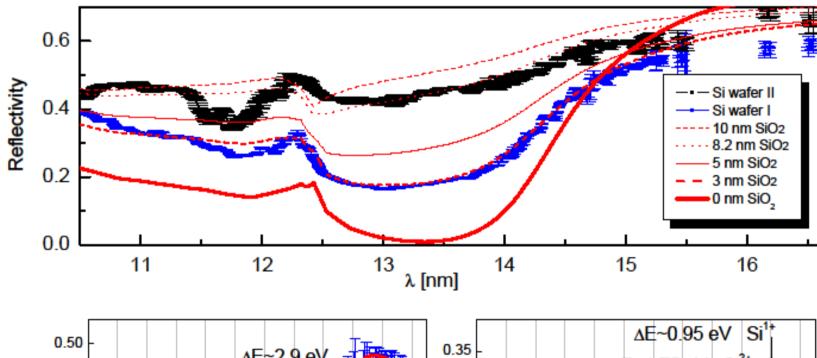
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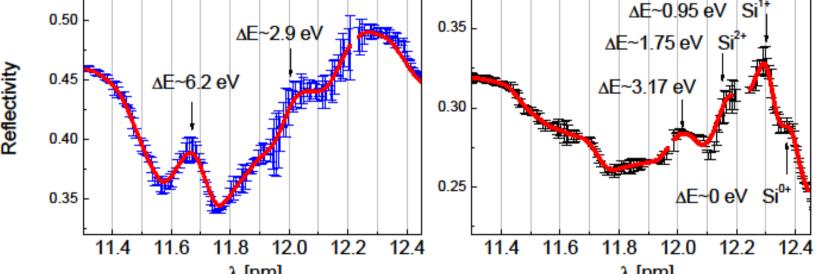
Abstract

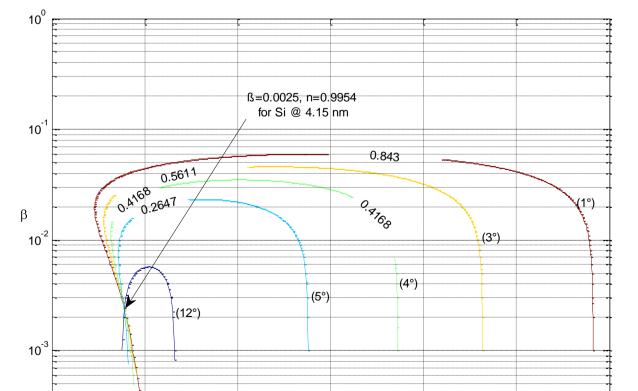
Extreme ultraviolet and soft x-ray radiation (XUV, 1-50 nm, or EUV, at around 13.5 nm) enables a variety of new optical, analytical and imaging procedures. The distinct features of XUV light such as the short wavelength allow resolutions in the range of a few nanometers in printing or imaging. Its strong interaction with matter permits high elemental contrast and photochemical sensitivity. Taking into account the recent progress in the development of sources and optics, XUV applications in the semiconductor industry, thin-film technology, life- and material sciences are envisioned. Examples are the determination of element composition, layer thickness and surface roughness from grazing incidence reflectivity or defect characterization from scattered light measurements using EUV dark field microscopy. Relevant applications are, e.g., mapping of mask blanks for EUV lithography, which requires the ability to scan large surfaces for the presence of small printable defects as rapid as possible or the examination of ultra-thin gate oxides or interlayers.

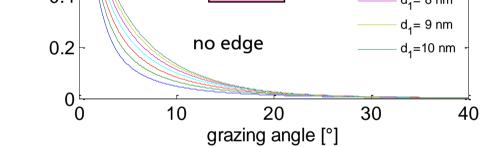


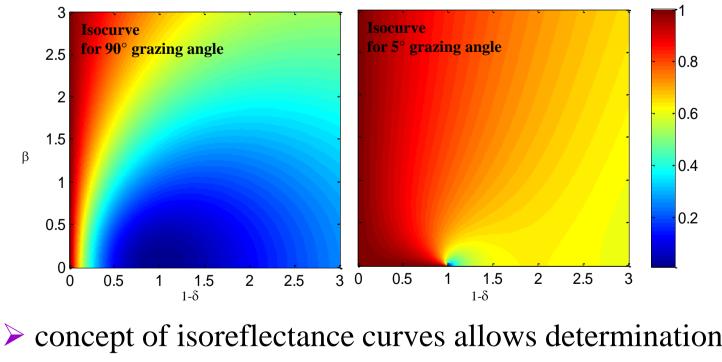


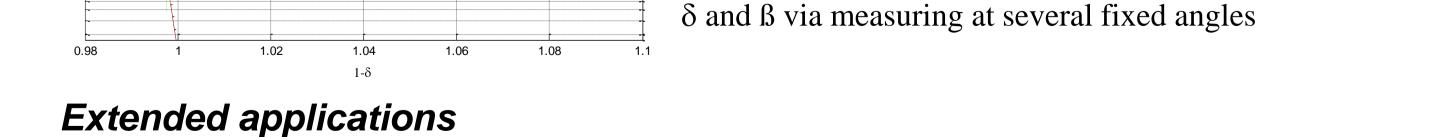


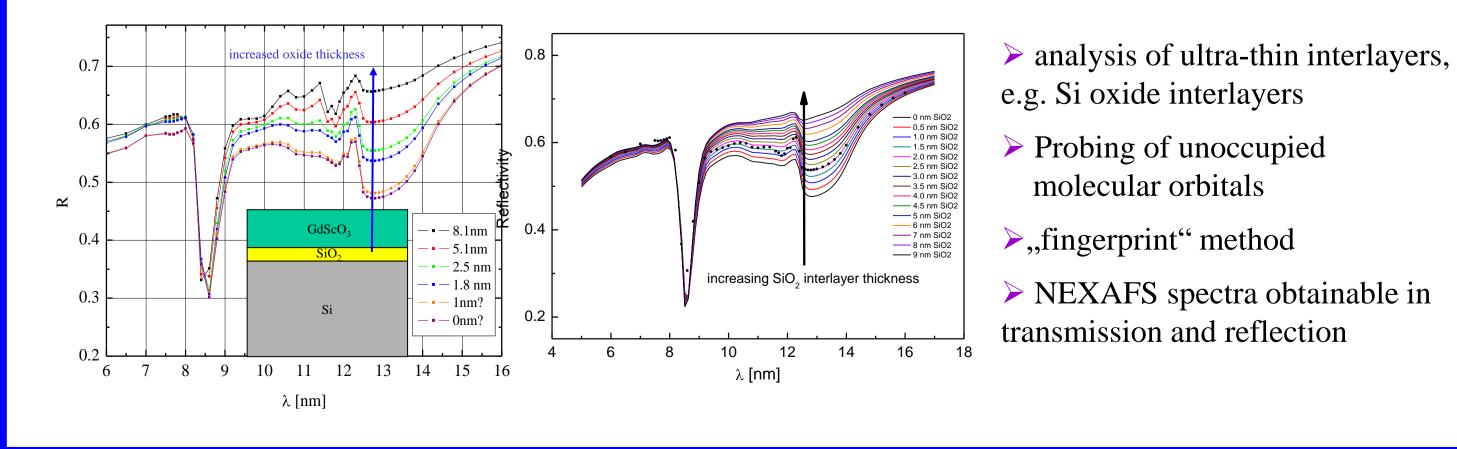


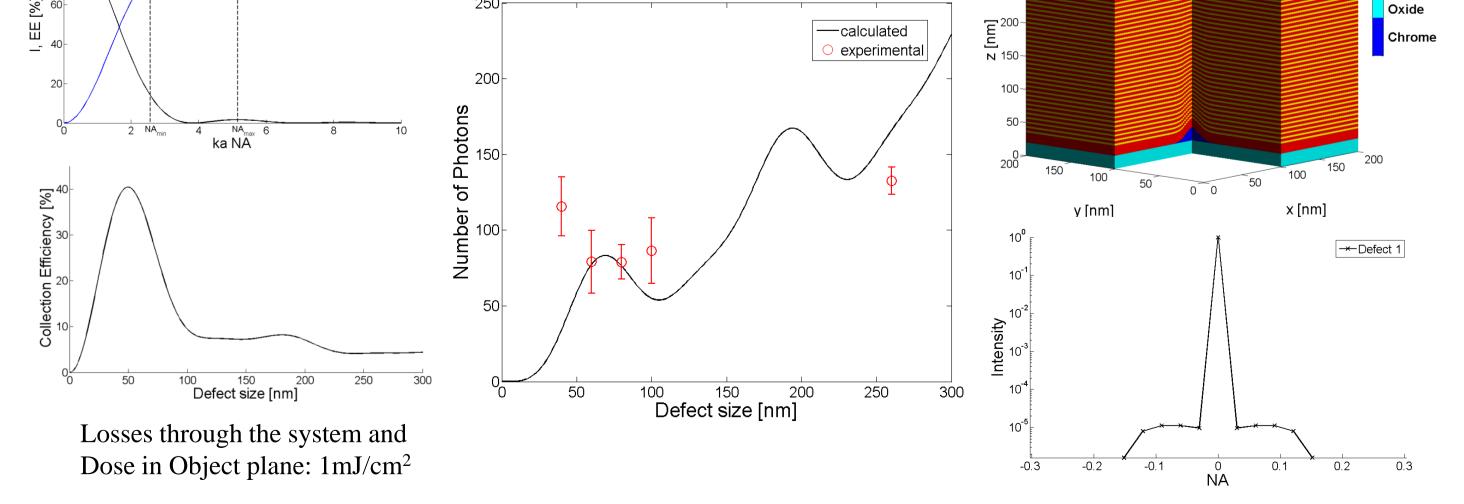












Adaption of more precise rigorous model to pinhole approach is work in progress

